



Mercury Device Thermal Resistance

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Data Sheet

Table 1 in this data sheet provides θ_{JA} (junction-to-ambient thermal resistance) and θ_{JC} (junction-to-case thermal resistance) values for Altera[®] Mercury[™] devices available in FineLine[®] Ball-Grid Array (FBGA).



For additional packaging information, refer to the *Altera Device Packaging Data Sheet*.

Device	Pin Count	Package	θ_{JC} (° C/W)	θ_{JA} (° C/W) Still Air	θ_{JA} (° C/W) 100 ft./min.	θ_{JA} (° C/W) 200 ft./min.	θ_{JA} (° C/W) 400 ft./min.
EP1M120	484	FBGA (Cu lid)	0.58	12.2	10.1	8.7	7.5
	484	FBGA (AlSiC lid)	0.87	13.0	11.1	9.3	7.9
EP1M350	780	FBGA (Cu lid)	0.22	10.5	8.5	7.1	5.9
	780	FBGA (AlSiC lid)	0.34	11.0	9.2	7.6	6.3



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